As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METALLIZATION STRUCTURES FOR SEMICONDUCTOR DEVICE INTERCONNECTS, METHODS FOR MAKING SAME, AND SEMICONDUCTOR DEVICES INCLUDING SAME, the specification of which (check one):

□ was filed on	as United States application serial noas PCT international application no	and was amended under PCT Article 19 on	•	
		e-identified specification, including the claims, as an	nended by any amendment	
referred to above.				
I acknowledge the duty to discl matter claimed in this application,	ose to the U.S. Patent and Trademark Office as "materiality" is defined in Title 37, Code	e all information known to me to be material to the p of Federal Regulations § 1.56.	patentability of the subject	
I hereby claim foreign priority	benefits under Title 35, United States Code	§ 119(a)-(d) or § 365(b) of any foreign application	(s) for patent or inventor's	
ertificate or § 365(a) of any PCT	international application(s) designating at least a least identified below and on any attached	ast one country other than the United States of Amer continuation page any foreign application for patent	rica listed below and on an	
PCT international application(s) devolute priority is claimed.	signating at least one country other than the	United States of America having a filing date before	that of the application(s)	
Prior foreign/PCT application(s):				
Tion foreign PCT application(s).			Priority Claimed	
(number)	(coun	try) (day/month/year filed)	Yes N	
(number)	(coun	try) (day/month/year filed)	Yes N	
pplication is not disclosed in any luty to disclose to the U.S. Patent	such prior application in the manner provide and Trademark Office all information know	inuation page and, insofar as the subject matter of ed by the first paragraph of Title 35, United States Contone to be material to patentability as defined in application and the national or PCT international	Code, § 112, I acknowledg Title 37, Code of Federal	
(application serial no.)	(filing date)	(status - pending, patente	(status - pending, patented or abandoned)	
(application serial no.)	(filing date)	(status - pending, patente	ed or abandoned)	
I hereby claim the benefit unde	r Title 35, United States Code, § 119(e) of a	any United States provisional application(s) listed be	low:	
(provisional application	no.) (filing date)			
I hereby appoint the following herewith:	Registered Practitioners to prosecute this app	plication and to transact all business in the Patent and	d Trademark Office conne	
David V. Trask, Reg. No. 22,6 Laurence B. Bond, Reg. No. 3 Allen C. Turner, Reg. No. 33, Stephen R. Christian, Reg. No. Paul C. Oestreich, Reg. No. P-	0,549 Joseph A. Walkowski, Reg 041 Kent S. Burningham, Reg. 32,687 Brick G. Power, Reg. No.	No. 28,765 James R. Duzan, Reg. No. 2 No. 30,453 Edgar R. Cataxinos, Reg. N 38,581 Kenneth B. Ludwig, Reg. N	28,393 To. 39,931 To. 42,814	
Kenneth C. Booth, Reg. No. 4. Lia M. Pappas, Reg. No. 34,0	2,342 Samuel E. Webb, Reg. No.	44,394 Michael L. Lynch, Reg. No	. 30,871	
Address all correspondence to:	Joseph A. Walkowski, telephone no TRASK, BRITT & ROSSA P.O. BOX 2550 Salt Lake City, Utah 84110	. (801) 532-1922.		
nd further that these statements wander Section 1001 of Title 18 of	ents made herein of my own knowledge are ere made with the knowledge that willful fal	true and that all statements made on information and se statements and the like so made are punishable b false statements may jeopardize the validity of the a	y fine or imprisonment, o	
hereon.	~ A		· ()-	
Full name of sole inventor: Salma inventor's signature Residence: Boise, Idaho	n Akram Salian AX	ram Date August 3	1999	
Citizenship: Pakistan Post Office Address: 1463 E. Reg	atta, Boise, Idaho 83706			